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Choi et al.

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(54) LIGHT EMITTING DIODE PACKAGE

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(*) Notice: This patent is subject to a terminal disclaimer.

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USPC D13/180

(58) Field of Classification Search

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See application file for complete search history.

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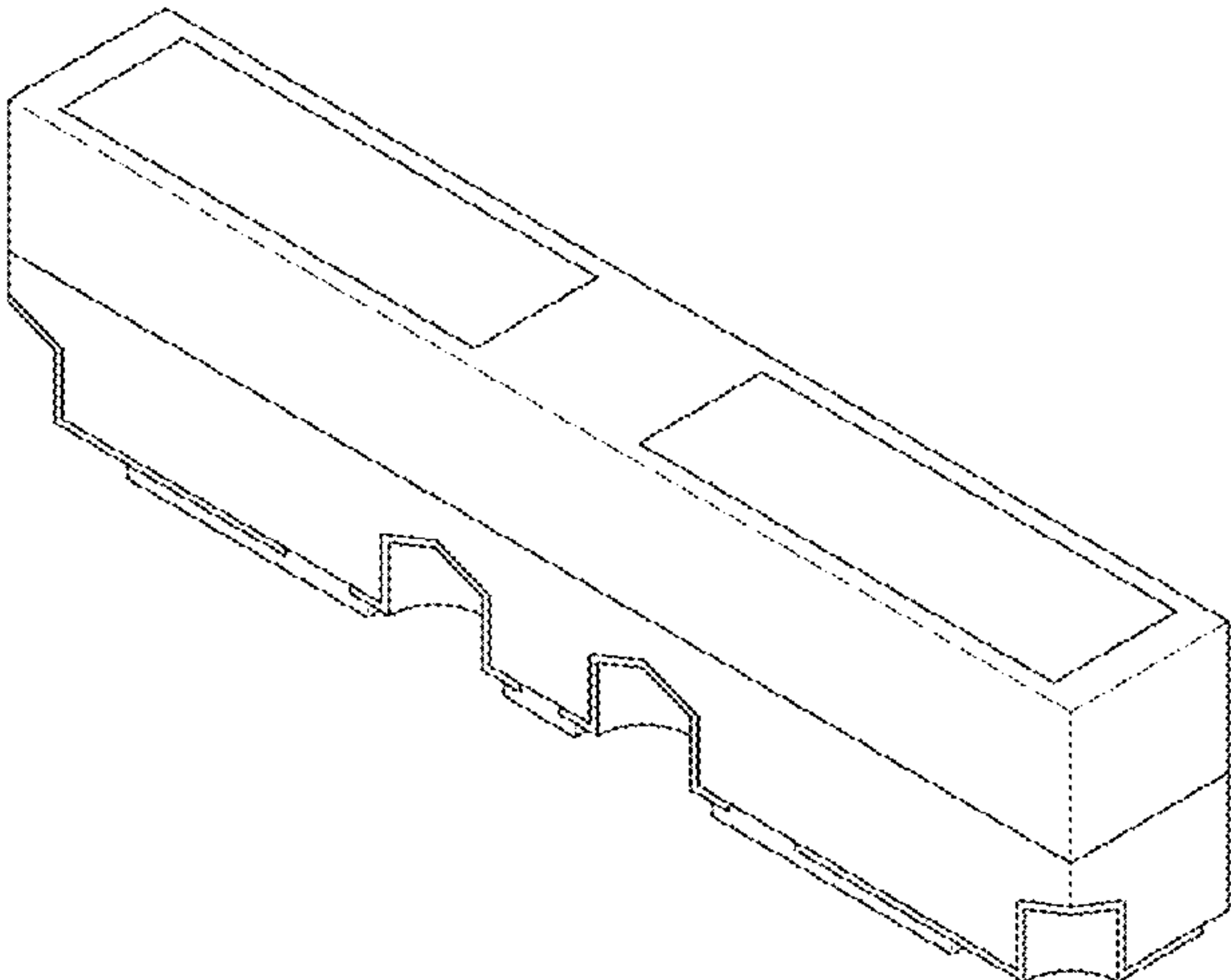
(57) CLAIM

The ornamental design for light emitting diode package, as shown and described.

DESCRIPTION

1. Light emitting diode package
- 1.1 : Perspective
- 1.2 : Front
- 1.3 : Back
- 1.4 : Left
- 1.5 : Right
- 1.6 : Top
- 1.7 : Bottom

1 Claim, 7 Drawing Sheets



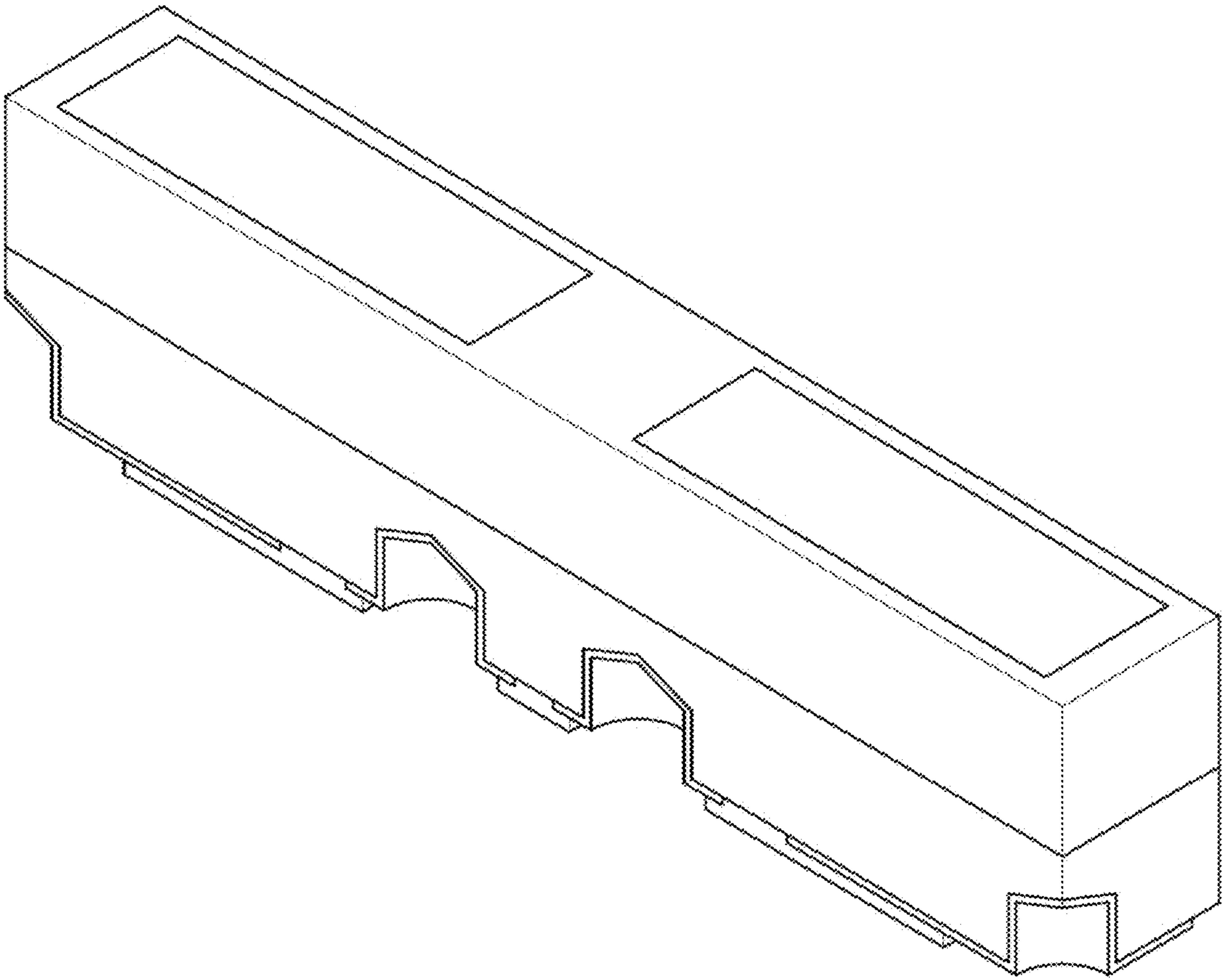
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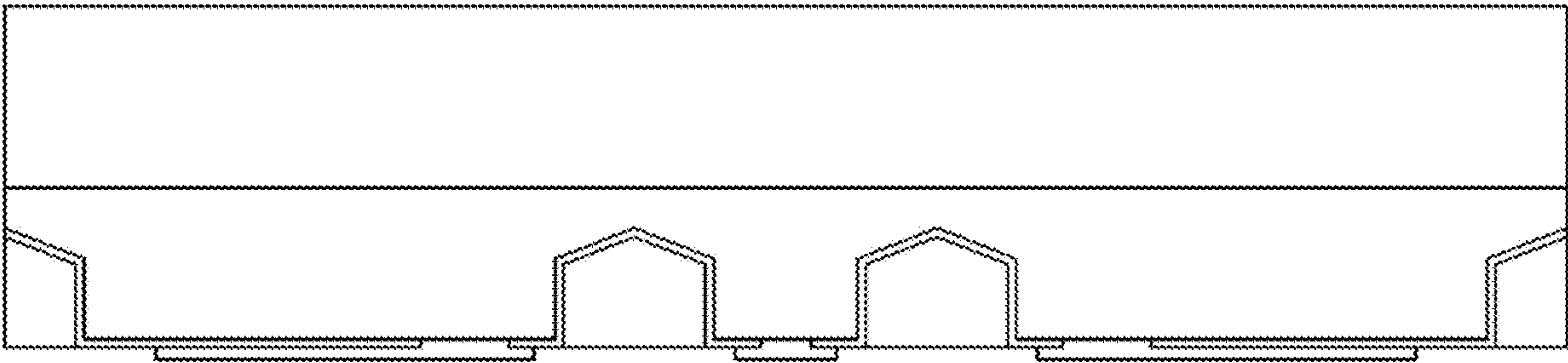
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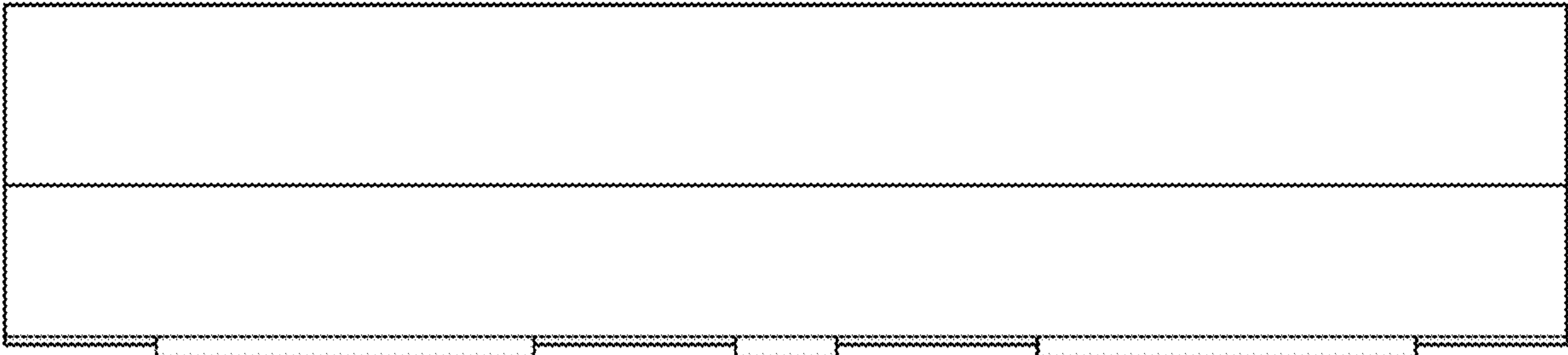
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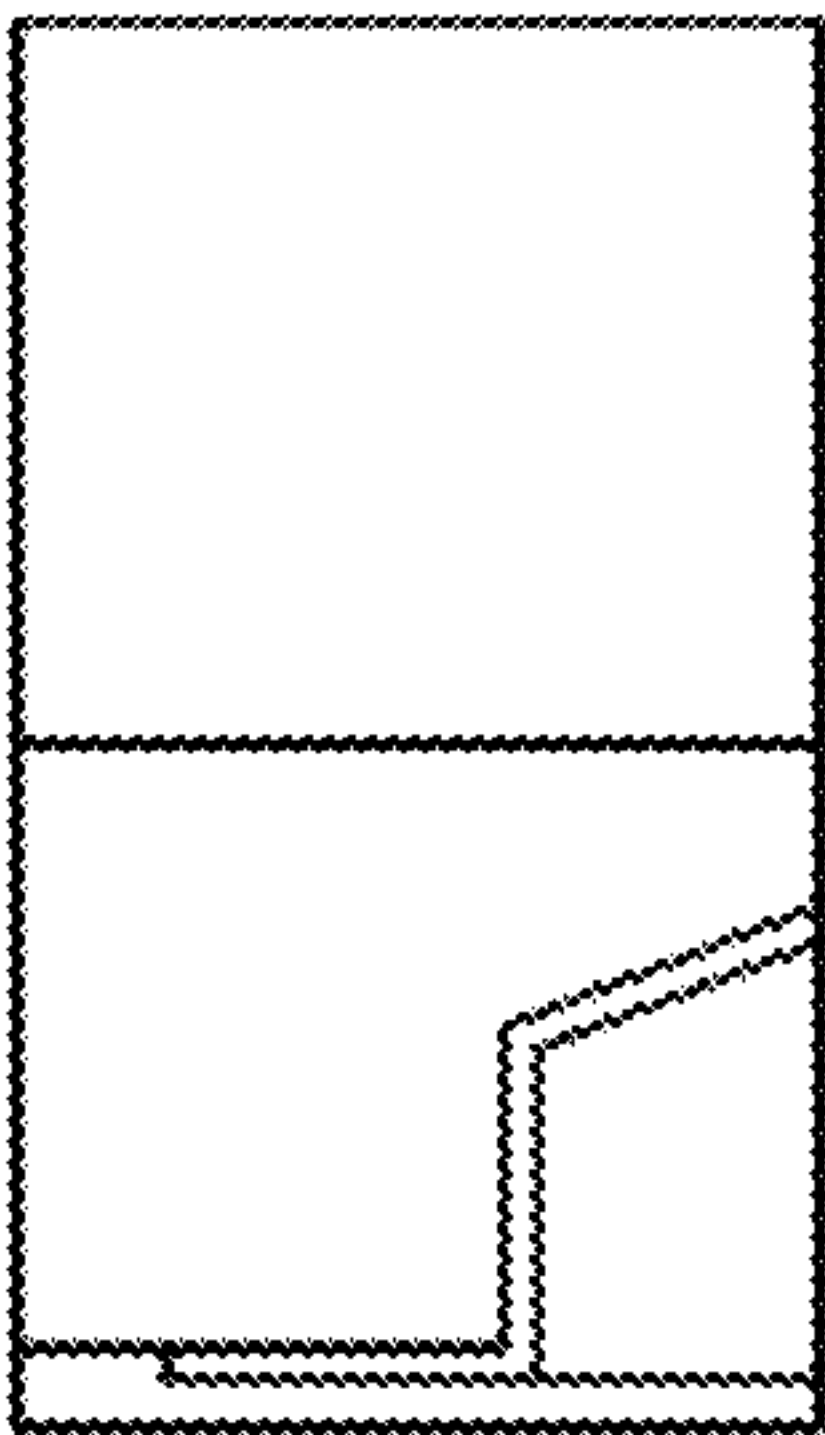
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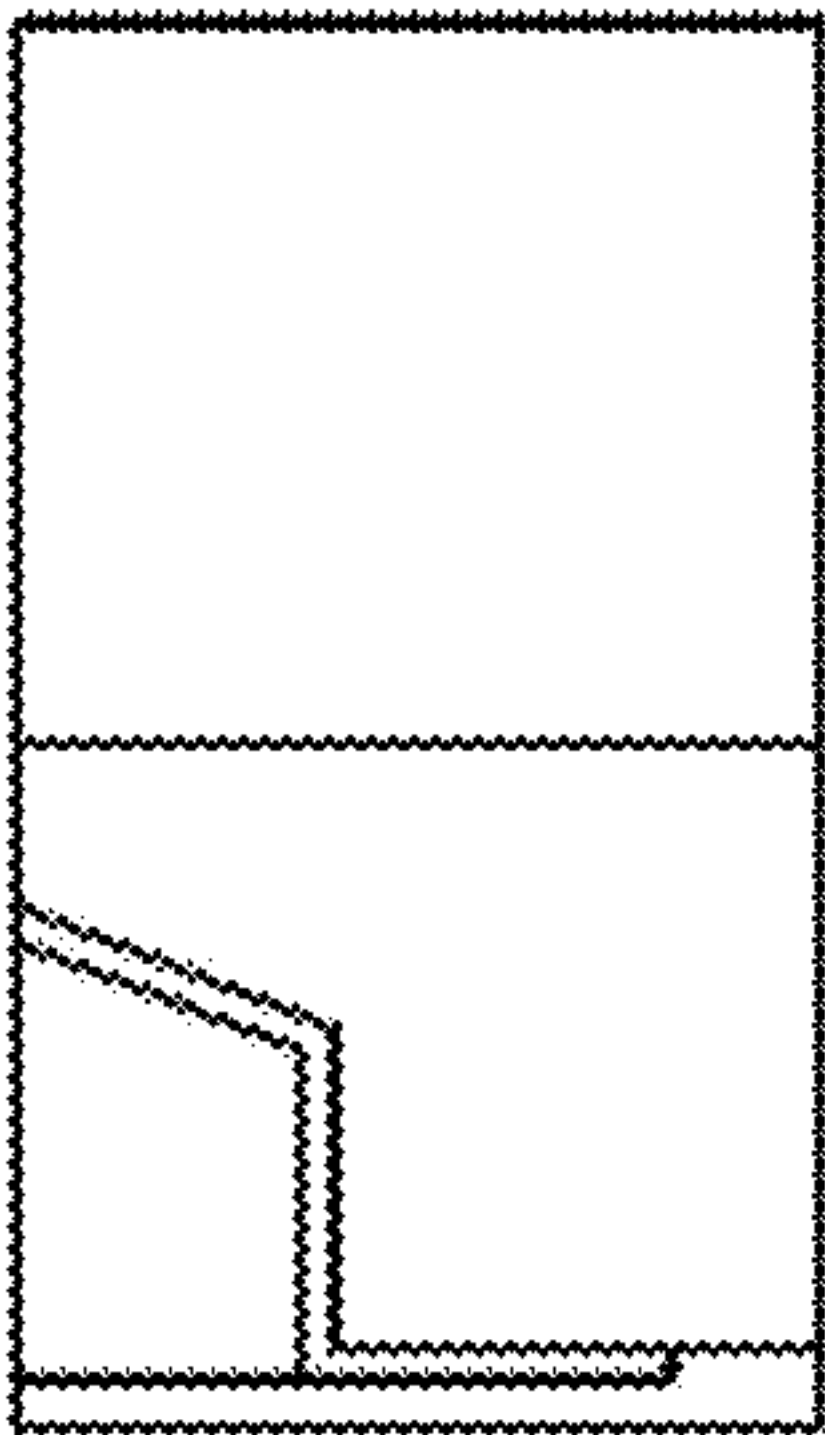
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